

#6/keopm Dkm PATENT 5-1-03 (5298-04500/PM00026)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re Application of: Li, et al.

Serial No. 09/849,047

Filed: May 4, 2001

For:

BURIED LAYER SUBSTRATE

ISOLATION IN INTEGRATED

CIRCUITS

Group Art Unit: 2822 Examiner: Lewis, M.

Atty. Dkt. No. 5298-04500

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on the date indicated below:

April 23, 2003 Date

Pamela Gerik

RESPONSE TO OFFICE ACTION MAILED JANUARY 31, 2003

Commissioner for Patents Washington, D.C. 20231

Dear Madame:

This paper is submitted in response to the Office Action mailed January 31, 2003 to further highlight reasons why the application is in condition for allowance.

Remarks/Arguments begin on page 2 of this paper.

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TECHNOLUGY CENTER 2800